

IN THE SPECIFICATION:

Please amend paragraph number [0004] as follows:

[0004] One common variation on this arrangement is to eliminate the die support pad or paddle and attach the semiconductor device to the lead fingers of the lead frame using an alpha barrier such as a polyamide tape, for example Kapton™ tape. In such an arrangement, a so-called ~~“leads-over-chip”~~ “leads-over-chip” arrangement (“LOC”), a plurality of lead fingers extend over the active surface of a semiconductor device toward one or more lines of bond pads wherein bond wires make the electrical connection between the lead fingers and the bond pads. Examples of such LOC configurations are shown in U.S. Patent 4,862,245 to Pashby and U.S. Patent 5,286,679 to Farnsworth et al. assigned to the assignee of the present invention.

Please amend paragraph number [0013] as follows:

[0013] Fig. 1 is a schematic top view of a semiconductor integrated circuit device in accordance with the present invention including a first embodiment of an extended lead ~~finger~~. finger;

Please amend paragraph number [0014] as follows:

[0014] Fig. 2 is a close-up partial top view of the lead frame configuration of Fig. 1 in accordance with the present ~~invention~~. invention;

Please amend paragraph number [0015] as follows:

[0015] Fig. 3 is a close-up partial top view of a lead frame configuration in accordance with the present invention including a second embodiment of an extended lead ~~finger~~. finger; and

Please amend paragraph number [0021] as follows:

[0021] Referring to drawing Fig. 3, a second embodiment of the present invention shows a semiconductor device including a portion of a modified conventional-type lead frame 12. The lead frame 12 includes a plurality of lead fingers 18 that extend toward the center of lead frame 12. Each of the lead fingers 18 includes a lead end 20 at a proximal end that is wire bonded to the semiconductor device 14 by wire bond 22 and a lead connection (not shown) at a distal end for electrically connecting the completed IC package. The lead fingers 18 are electrically connected, as described hereinbefore, to the bond pads 38 of the semiconductor device 14 by a wire bond 22.